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HMA: SAVING ADHESIVE THROUGH TEMPERATURE CONTROL

HMA is used in large quantities in the packaging industry, primarily to bond corrugated cardboard into boxes. The bonding is very quickly, but good interaction between the paper and HMA is required. This can only take place as long as the HMA is still sufficiently liquid. This depends on the actual adhesive temperature during the bonding process.

Suitable temperature control of the paper can extend the interaction phase of the adhesive with the paper and a larger bonding surface is also achieved. Both lead to an interesting potential savings in the amount of adhesive used.